

Parameter	Rating	Units
Blocking Voltage	60	V _P
Load Current	4	A _{DC}
On-Resistance (max)	0.09	Ω

Features

- Handle Load Currents Up to 4A_{DC}
- 2500V_{rms} Input/Output Isolation
- Power SIP Package
- High Reliability
- · No Moving Parts
- Low Drive Power Requirements (TTL/CMOS Compatible)
- · Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- · Machine Insertable, Wave Solderable

Applications

- Industrial Controls
- Motor Control
- Robotics
- Medical Equipment—Patient/Equipment Isolation
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- · Meters (Watt-Hour, Water, Gas)
- IC Equipment
- Home Appliances

Description

IXYS Integrated Circuits Division and IXYS have combined to bring OptoMOS® technology, reliability, and compact size to a new family of high power solid state relays. The CPC1706, a DC-switching, normally open (1-Form-A) Solid State Relay, is part of that family.

Employing optically coupled MOSFET technology, the CPC1706 provides 2500V_{rms} of input to output isolation. The relay output is constructed with efficient MOSFET switches that use IXYS Integrated Circuits Division's patented OptoMOS architecture. The input, a highly efficient GaAIAS infrared LED, controls the optically coupled output.

The combination of low on-resistance and high load current handling capability makes this relay suitable for a variety of high performance switching applications.

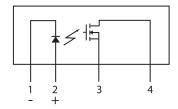
Approvals

- UL 508 Certified Component: File E69938
- CSA Certified Component: Certificate 1172007

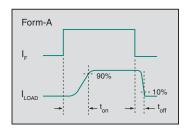
Ordering Information

Part #	Description
CPC1706Y	4-Pin (8-Pin Body) Power SIP Package (25 per tube)

Pin Configuration



Switching Characteristics of Normally Open Devices











Absolute Maximum Ratings @ 25°C

Parameter	Min	Max	Units
Blocking Voltage	-	60	V_{P}
Reverse Input Voltage	-	5	V
Input control Current	-	50	mA
Peak (10ms)	-	1	Α
Input Power Dissipation ¹	-	150	mW
Total Power Dissipation ²	-	1600	mW
Isolation Voltage, Input to Output	-	2500	V _{rms}
Operational Temperature	-40	+85	°C
Storage Temperature	-40	+125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics	'		'			'
Load Current, Continuous	I _F =5mA, Free air	I _L	-	-	4	A _{DC}
Peak Load Current	I _F =5mA, t=10ms	I _{LPK}	-	-	9	A
On-Resistance ¹	I _F =5mA, I _I =1A	R _{on}	-	0.07	0.09	Ω
Off-State Leakage Current	I _F =0mA, V _I =60V _P	I _{LEAK}	-	-	1	μΑ
Switching Speeds		227111				
Turn-On	I 5 A V 40V	t _{on}	-	0.5	5	
Turn-Off	I _F =5mA, V _L =10V	t _{off}	-	0.085	2	ms
Output Capacitance	I _F =0mA, V _I =50V, f=1MHz	C _{OUT}	-	75		pF
Input Characteristics	,		1	1		1
Input Control Current to Activate	I,=1A	l _F	-	1.4	5	mA
Input Control Current to Deactivate	-	l _F	0.4	-		mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μΑ
Input/Output Characteristics	,		1	-1		'
Capacitance Input/Output	f=1MHz	C _{I/O}	-	2	-	pF

¹ Measurement taken within 1 second of on-time.

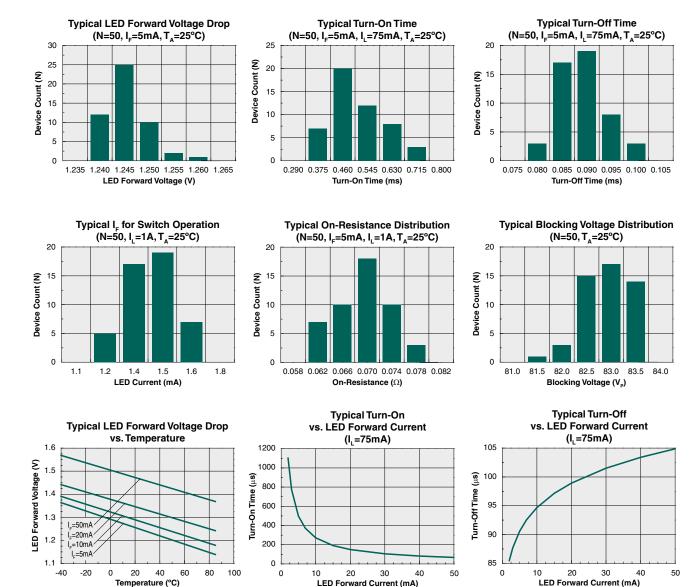
Thermal Characteristics

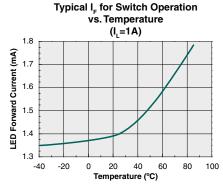
Parameter	Conditions	Symbol	Min	Тур	Max	Units
Thermal Resistance (junction to case)	-	$R_{ heta JC}$	-	1.5	-	°C/W

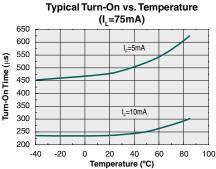
Derate linearly 3.33 mW / °C
Derate linearly 16.667 mW / °C

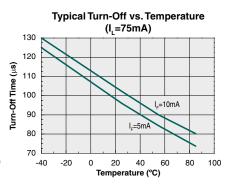


PERFORMANCE DATA*





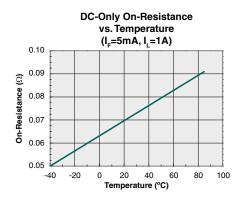


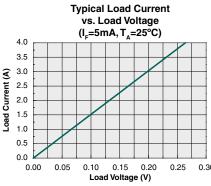


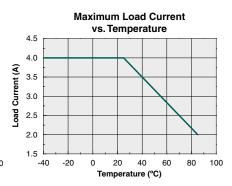
^{*} The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

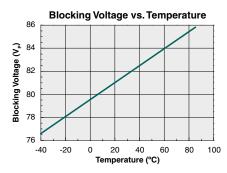


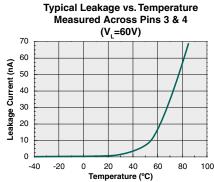
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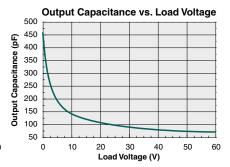


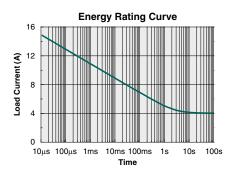












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Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating		
CPC1706Y	MSL 1		

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time		
CPC1706Y	245°C for 30 seconds		

Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

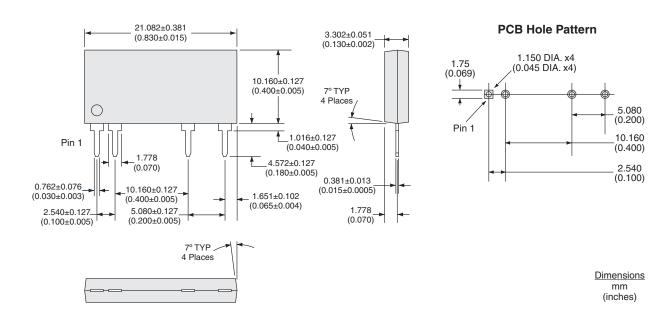








MECHANICAL DIMENSIONS



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